



Material Content Data Sheet



Sales Product Name		XMC1301-T038F0032 AB		Issued		14. September 2015		
MA#		MA001408470						
Package		PG-TSSOP-38-9		Weight*		118.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.226	1.04	1.04	10353	10353
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	zinc	7440-66-6	0.060	0.05		506	
	non noble metal	iron	7439-89-6	1.199	1.01		10126	
wire	non noble metal	copper	7440-50-8	48.679	41.12	42.19	411170	421929
	noble metal	palladium	7440-05-3	0.003	0.00		27	
encapsulation	non noble metal	copper	7440-50-8	0.311	0.26	0.26	2629	2656
	organic material	carbon black	1333-86-4	0.192	0.16		1620	
	plastics	epoxy resin	-	7.479	6.32		63167	
leadfinish	inorganic material	silicondioxide	60676-86-0	56.249	47.52	54.00	475102	539889
	non noble metal	tin	7440-31-5	2.200	1.86	1.86	18580	18580
plating	noble metal	silver	7440-22-4	0.337	0.28	0.28	2849	2849
glue	plastics	epoxy resin	-	0.111	0.09		936	
	noble metal	silver	7440-22-4	0.332	0.28	0.37	2808	3744
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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